

## **PCB** laminate parameters

PCB Supplier	Suppliers choice
Number of copper layers	4 layers
Laminate material	FR4
Total board thickness	1.6mm
PCB stackup	See figure 1
Copper thickness	See figure 1
Solder Mask Color	Green
Silkscreen Color	White
Surface finish	ENIG Gold
Compliance with environmental directives	RoHS

Table 1 PCB substrate details

The PCB layer stackup order (from top layer and down) shall be as follows with reference to the Gerber file extensions given below:

Top layer: .GTL
Mid-layer 1: .G1
Mid-layer 2: .G2
Bottom Layer: .GBL

LAYER	NAME OF LAYER	TYPE	THICKNESS mm	VIAS
1	EXTERNAL COPPER	12μm + GalvCu 35μm	0.047	
	PREPREG	7628-45 (0,18mm)	0.18	
2	INNER FOIL	35µm	0.035	
	INNERLAYER	High Tg 1,08mm 35μm/35μm	1.08	
3	INNER FOIL	35µm	0.035	
	PREPREG	7628-45 (0,18mm)	0.18	
4	EXTERNAL COPPER	12μm + GalvCu 35μm	0.047	
		THICKNESS (mm) ±10%	1.604	

Figure 1: 4 layer stackup